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May 2014

# FDD9409\_F085

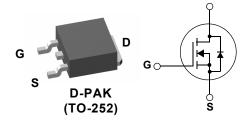
# N-Channel PowerTrench® MOSFET **40 V, 90 A, 3.2 m**Ω

#### **Features**

- Typ R<sub>DS(on)</sub> = 2.3m $\Omega$  at V<sub>GS</sub> = 10V, I<sub>D</sub> = 80A
- Typ  $Q_{g(tot)}$  = 42nC at  $V_{GS}$  = 10V,  $I_{D}$  = 80A
- UIS Capability
- RoHS Compliant
- Qualified to AEC Q101

#### **Applications**

- Automotive Engine Control
- Powertrain Management
- Solenoid and Motor Drivers
- Electronic Steering
- Integrated Starter/Alternator
- Distributed Power Architectures and VRM
- Primary Switch for 12V Systems





For current package drawing, please refer to the Fairchild website at www.fairchildsemi.com/packaging

### **MOSFET Maximum Ratings** T<sub>J</sub> = 25°C unless otherwise noted.

Symbol	Parameter		Ratings	Units	
$V_{DSS}$	Drain-to-Source Voltage		40	V	
$V_{GS}$	Gate-to-Source Voltage	±20	V		
ı			90	A	
ID			See Figure 4		
E <sub>AS</sub>	Single-Pulse Avalanche Energy	101	mJ		
D	Power Dissipation		150	W	
$P_{D}$	Derate Above 25°C		1	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature	-55 to + 175	°C		
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1	°C/W		
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	52	°C/W	

## **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD9409	FDD9409_F085	D-PAK(TO-252)	13"	12mm	2500 units

#### Notes:

- 1: Current is limited by bondwire configuration.
- Current is inflied by borlowine configuration.
   Starting T<sub>J</sub> = 25°C, L = 0.1mH, I<sub>AS</sub> = 44A, V<sub>DD</sub> = 40V during inductor charging and V<sub>DD</sub> = 0V during time in avalanche.
   R<sub>θJA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>θJC</sub> is guaranteed by design while R<sub>θJA</sub>is determined by the user's board design. The maximum rating presented here is based on mounting on a 1 in<sup>2</sup> pad of 2oz copper.

Units

Max.

# **Electrical Characteristics** $T_J = 25^{\circ}C$ unless otherwise noted.

**Parameter** 

Off Characteristics								
B <sub>VDSS</sub>	Drain-to-Source Breakdown Voltage	I <sub>D</sub> = 250μA, \	/ <sub>GS</sub> = 0V	40	-	-	V	
I <sub>DSS</sub>	Drain-to-Source Leakage Current	V <sub>DS</sub> =40V,	$T_J = 25^{\circ}C$	-	-	1	μΑ	
		$V_{GS} = 0V$	$T_J = 175^{\circ}C(Note 4)$	-	-	1	mA	
lass	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		-	_	±100	nA	

**Test Conditions** 

Min.

Тур.

### On Characteristics

Symbol

V <sub>GS(th)</sub>	Gate-to-Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	3.2	4.0	V
R <sub>DS(on)</sub> Drain-to-Source On Resistance	Drain to Source On Posistance	I <sub>D</sub> = 80A,	$T_{J} = 25^{\circ}C$	-	2.3	3.2	$m\Omega$
	V <sub>GS</sub> = 10V	$T_J = 175^{\circ}C(Note 4)$	-	4.1	5.7	$m\Omega$	

## **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		-	3130	-	pF
C <sub>oss</sub>	Output Capacitance			-	756	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			-	48	-	pF
$R_g$	Gate Resistance	f = 1MHz		-	2	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	V <sub>DD</sub> = 20V	-	42	46	nC
Q <sub>g(th)</sub>	Threshold Gate Charge	$V_{GS} = 0$ to 2V	I <sub>D</sub> = 80A	-	6	7	nC
$Q_{gs}$	Gate-to-Source Gate Charge		_	-	16	-	nC
$Q_{gd}$	Gate-to-Drain "Miller" Charge			-	7.7	-	nC

## **Switching Characteristics**

t <sub>on</sub>	Turn-On Time	$V_{DD} = 20V, I_{D} = 80A,$ $V_{GS} = 10V, R_{GEN} = 6\Omega$	-	-	72	ns
t <sub>d(on)</sub>	Turn-On Delay		-	23	-	ns
t <sub>r</sub>	Rise Time		-	22	-	ns
t <sub>d(off)</sub>	Turn-Off Delay		-	41	-	ns
t <sub>f</sub>	Fall Time		-	15	-	ns
t <sub>off</sub>	Turn-Off Time		-	-	76	ns

### **Drain-Source Diode Characteristics**

IVon Source-to-Drain Diode Voltage	Source to Drain Diede Voltage	I <sub>SD</sub> = 80A, V <sub>GS</sub> = 0V	-	-	1.25	V
	$I_{SD} = 40A, V_{GS} = 0V$	-	-	1.2	V	
t <sub>rr</sub>	Reverse-Recovery Time	$I_F = 80A$ , $dI_{SD}/dt = 100A/\mu s$ ,	-	54	73	ns
Q <sub>rr</sub>	Reverse-Recovery Charge	V <sub>DD</sub> =32V	-	42	61	nC

#### Note

4: The maximum value is specified by design at TJ = 175°C. Product is not tested to this condition in production.

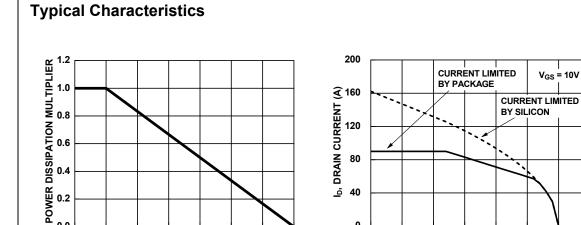


Figure 1. Normalized Power Dissipation vs. Case **Temperature** 

75

T<sub>C</sub>, CASE TEMPERATURE(°C)

100

125

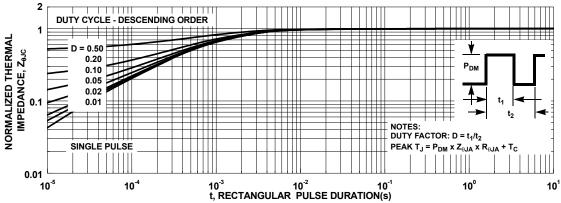
150

0.0

0

Figure 2. Maximum Continuous Drain Current vs. **Case Temperature** 

75 100 125 150 T<sub>C</sub>, CASE TEMPERATURE(°C)



0

Figure 3. Normalized Maximum Transient Thermal Impedance

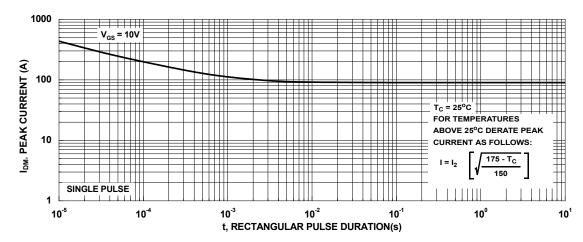


Figure 4. Peak Current Capability

# **Typical Characteristics**

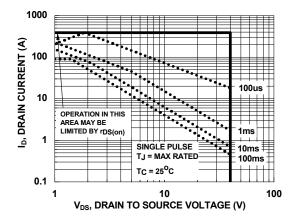
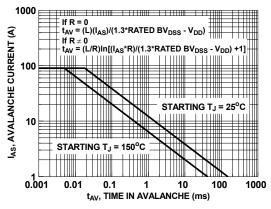


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

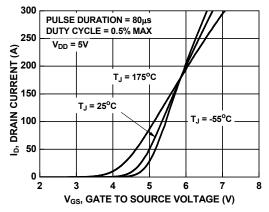


Figure 7. Transfer Characteristics

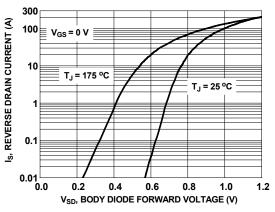


Figure 8. Forward Diode Characteristics

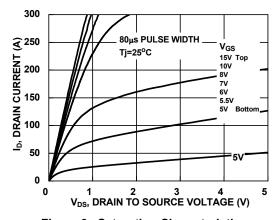


Figure 9. Saturation Characteristics

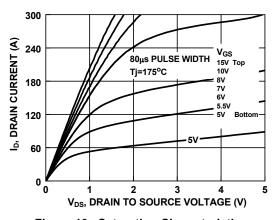


Figure 10. Saturation Characteristics

# **Typical Characteristics**

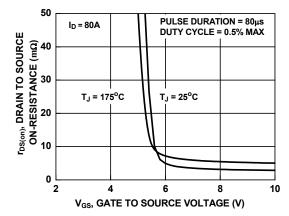


Figure 11. R<sub>DSON</sub> vs. Gate Voltage

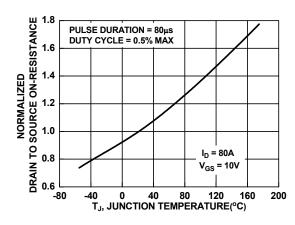


Figure 12. Normalized R<sub>DSON</sub> vs. Junction Temperature

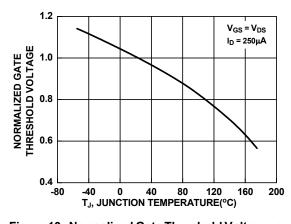


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

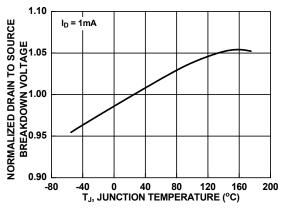


Figure 14. Normalized Drain--Source Breakdown Voltage vs. Junction Temperature

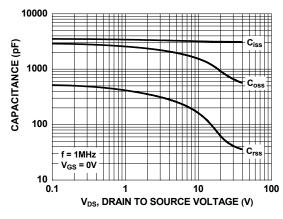


Figure 15. Capacitance vs. Drain--Source Voltage

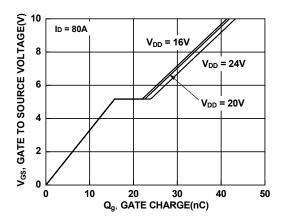


Figure 16. Gate Charge vs. Gate--Source Voltage





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